



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

# 13  
9/29/03 2815  
Mullen

In re the Application of:

Test, et al.

Serial No.: 09/817,696

Filed: 03/23/2001

For: Wire Bonding Process for Copper-Metallized Integrated Circuits

Conf. No.: 9347

Docket No.: TI-30589

Examiner: Richards, N. D.

Art Unit: 2815

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Response under 37 CFR 1.111

Commission for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on

9-16-03

Jackie McBride  
Jackie McBride

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 06/16/03. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.